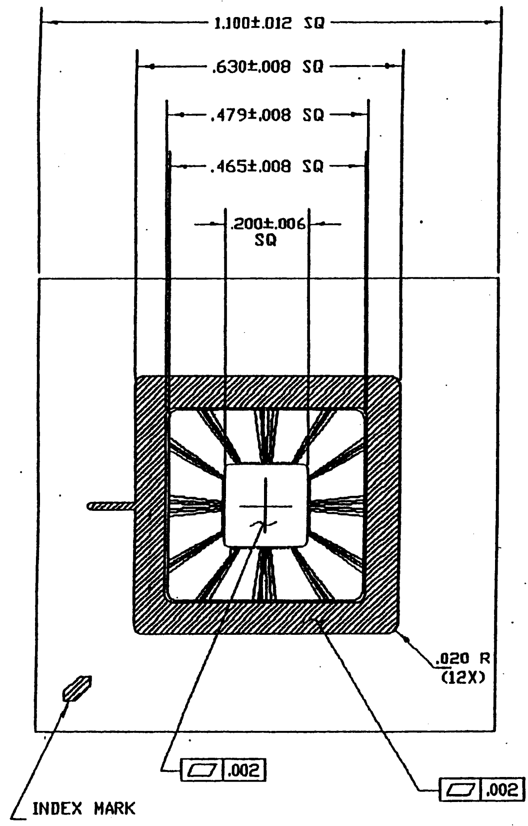
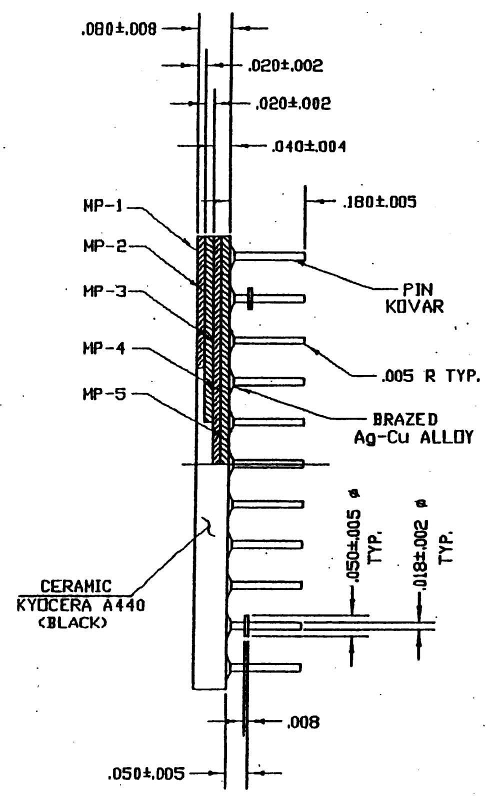
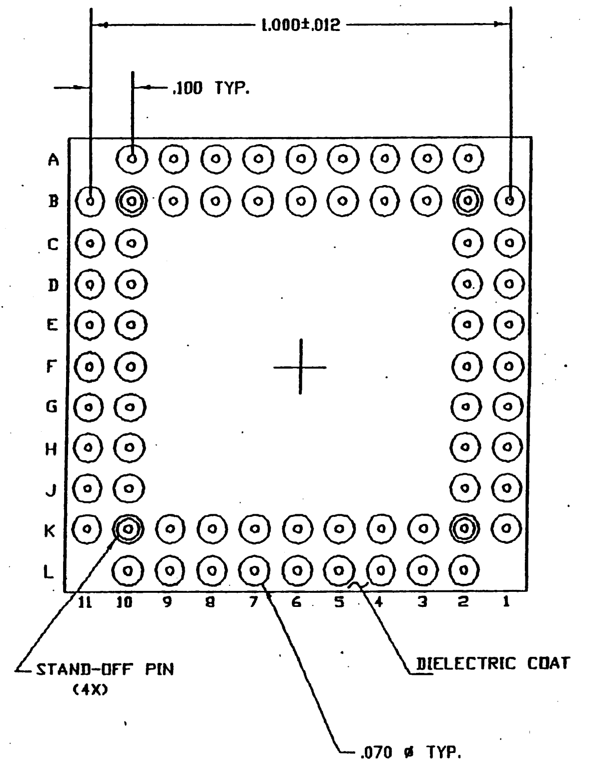
SSM P/N CPG06853

REVISIONS

ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
	**	563	NEW RELEASE	08/13/93	







NOTES:

1. GOLD PLATE 80 µ in 250 µ INCHES OVER 50 µ in 350 µ INCHES NICKEL.
2. SEAL RING AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH AREA TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE:
   B/F NO. 8, 9, 10, 34, 35, 68 .....400 mΩ MAX.
   THE OTHERS ....700 mΩ MAX.

UNLESS OTHERWISE SPECIFIED
ALL DIMENSIONS ARE IN INCHES

DRAWN: HTN DATE: 08/11/93

TITLE: 68 LD PGA 200 X 200

SIZE: C REV: **

FINISH: CPG06853

SCALE: 5 X SHEET 1 OF 2

www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226

SSM P/N CPG06853

REVISIONS					
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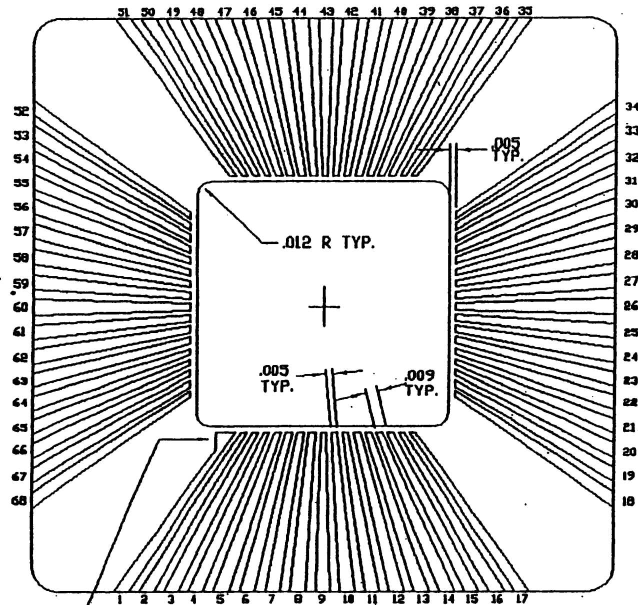

BONDING PATTERN

SCALE: 15: 1

AWIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.
1	K2
2	L2
3	K3
4	L3
5	K4
6	L4
7	K5
8	L5
9	K6
10	L6
11	K7
12	L7
13	K8
14	L8
15	K9
16	L9
17	L10
18	K10
19	K11
20	J10

W/B NO.	PIN NO.
21	J11
22	H10
23	H11
24	G10
25	G11
26	F10
27	F11
28	E10
29	E11
30	D10
31	D11
32	C10
33	C11
34	B11
35	B10
36	A10
37	B9
38	A9
39	B8
40	A8

W/B NO.	PIN NO.
41	B7
42	A7
43	B6
44	A6
45	B5
46	A5
47	B4
48	A4
49	B3
50	A3
51	A2
52	B2
53	B1
54	C2
55	C1
56	D2
57	D1
58	E2
59	E1
60	F2

W/B NO.	PIN NO.
61	F1
62	G2
63	G1
64	H2
65	H1
66	J2
67	J1
68	K1

S/R	NC
D/A	NC

UNLESS OTHERWISE SPECIFIED

ALL DIMENSIONS ARE IN INCHES

MATERIAL

FINISH

DRAWN HTN 08/11/93

TITLE 68 LD PGA 200 X 200

SIZE C

REV **

SCALE NOTED

SPECTRUM SEMICONDUCTOR MATERIALS, INC.

www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226